



Material Content Data Sheet



Sales Product Name		SAK-TC1797-512F180EF AC			Issued		31. January 2019		
MA#		MA001365410							
Package		P-BGA-416-27			Weight*		3230.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	54.869	1.70	1.70	16986	16986	
wire	non noble metal	copper	7440-50-8	4.217	0.13	0.13	1306	1306	
encapsulation	organic material	carbon black	1333-86-4	2.379	0.07		737		
	plastics	epoxy resin	-	146.331	4.53		45302		
substrate	inorganic material	silicondioxide	60676-86-0	1040.970	32.23	36.83	322267	368306	
	plastics	epoxy resin	-	22.546	0.70		6980		
	inorganic material	bariumsulfate	7727-43-7	34.597	1.07		10711		
	plastics	acrylic resin	-	40.039	1.24		12396		
	plastics	bismaleimide triazine resin	-	122.239	3.78		37843		
plating	inorganic material	aluminiumhydroxide	21645-51-2	134.463	4.16		41628		
	inorganic material	glass fibre	-	232.255	7.19		71902		
	non noble metal	copper	7440-50-8	961.301	29.76	47.90	297603	479063	
solderball	noble metal	gold	7440-57-5	5.548	0.17		1718		
	non noble metal	nickel	7440-02-0	5.548	0.17	0.34	1718	3436	
glue	non noble metal	lead	7439-92-1	153.661	4.76		47571		
	non noble metal	tin	7440-31-5	261.638	8.10	12.86	80999	128570	
*deviation	plastics	epoxy resin	-	1.884	0.06		583		
	noble metal	silver	7440-22-4	5.652	0.18	0.24	1750	2333	
						Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com